



Product Change Notification

Change Notification #: 115223 - 00
Change Title: Intel® Server System R2224WTTYSR,
PCN 115223-00, Product Design,
Bracket update and cover screw removal
Date of Publication: January 05, 2017

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	Jan 11, 2017
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R2224WTTYSR:

1. The width of the holes in the PCIe* Riser bracket will change from 2.4mm to 2.8mm.

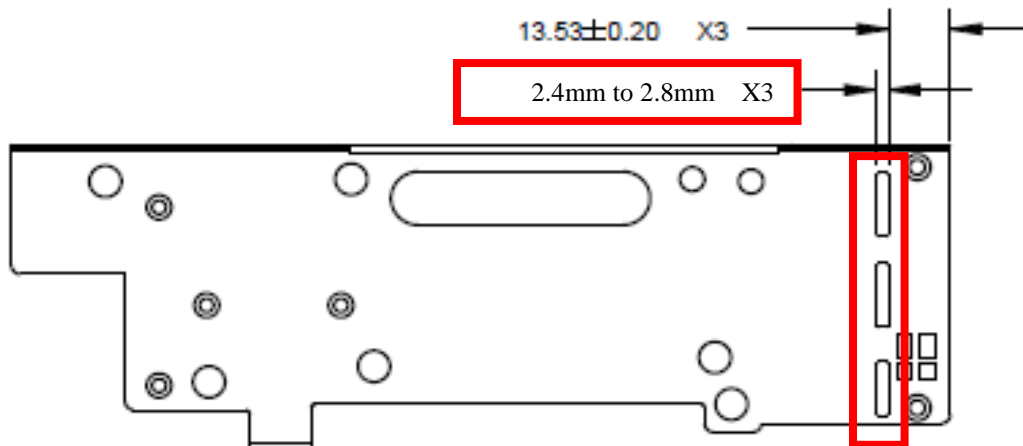


Figure 1. PCIe* Riser Bracket

- Screw from the Top Cover will be removed to provide tool-less assembly.

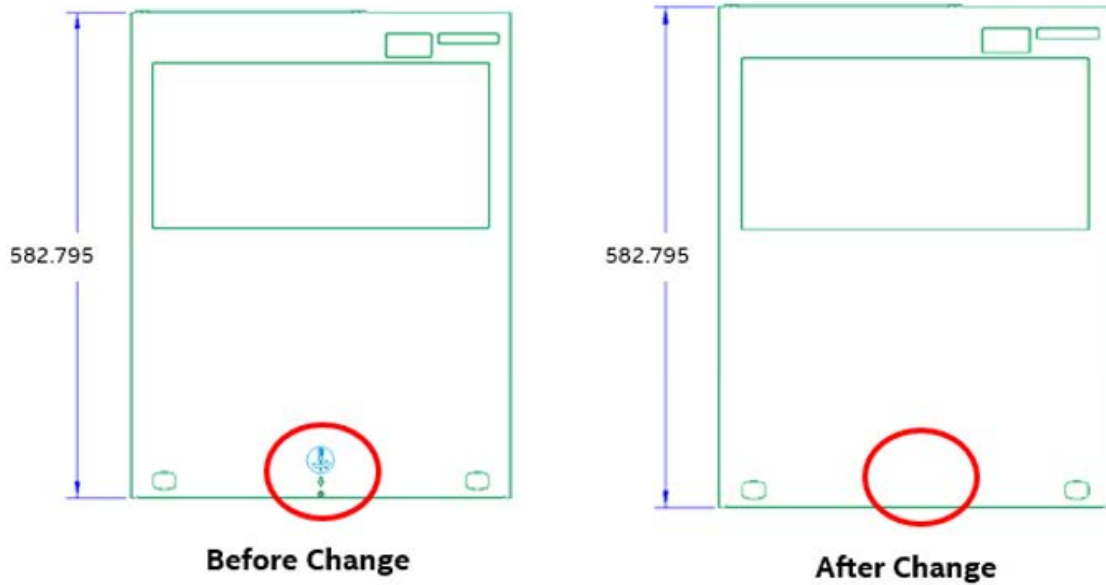


Figure 2. Remove the screw from the top cover

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
R2224WTTYSR	943831	J11492-005	J11492-006

PCN Revision History:

Date of Revision: January 5, 2017	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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